

## An Advanced Sample Structure for Excimer Laser Crystallization

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High-performance TFTs for “system on glass” cannot be made without introducing a lateral growth of Si grains by excimer laser annealing [1]-[4]. The optimization of laser light intensity profile by optical modulation, such as a phase-modulated excimer-laser annealing (PMELA) method, is very important to obtain long grains [5]. The sample structure plays also an important role since it determines solidification characteristics under fixed light intensity conditions. We have reported [6] that the optimum thickness of the SiO<sub>2</sub> capping layer is about 200 nm for a 200 nm-thick Si layer/SiO<sub>2</sub> layer structure. The growth length was about 5 μm at the light intensity of 700 mJ/cm<sup>2</sup> and 7 μm at 1000 mJ/cm<sup>2</sup>. The grain length is sufficiently large to install several TFTs with 1 μm-long channel in a grain.

It is desirable to decrease the light intensity further at the crystallization. Yeh et al. reported that long grains were grown with SiON capping layer, which is photosensitive for KrF excimer-laser [7]. In the present report, we focused attention on SiO<sub>x</sub> thin film in the pursuit of good photosensitive layers for wider range of laser wavelength. The optical properties of SiO<sub>x</sub> film can be changed by changing the value of x from 0 to 2. A SiO<sub>x</sub>/SiO<sub>2</sub> stacked structure was newly introduced for the capping.

Samples were of a stacked structure with PECVD 250 nm-thick SiO<sub>x</sub>/30 nm-thick SiO<sub>2</sub> double capping layers, a 200 nm-thick PECVD a-Si layer, and a 1000 nm-thick thermal SiO<sub>2</sub> layer on Si substrate as shown in Fig.1. The total thickness of SiO<sub>x</sub>/SiO<sub>2</sub> stacked capping layer was chosen to be 280nm so as to minimize the surface reflection by taking the multiple reflection effect into account. The value of absorption coefficient  $\alpha$  of the SiO<sub>x</sub> layer can be changed by varying the SiH<sub>4</sub>/N<sub>2</sub>O flow rate ratio in the CVD process as shown in Fig.2. We also made a reference sample with a single SiO<sub>2</sub> capping layer. Both samples had the same a-Si thicknesses. The light intensity to irradiate the a-Si layer of the (A) sample can be changed by changing the  $\alpha$  value of the SiO<sub>x</sub> film. There may be the optimum  $\alpha$  value. The optimum  $\alpha$  value is supposed to be 3000 to 5000 cm<sup>-1</sup> for this structure. This condition was satisfied at the flow rate ratio ranging from 22 % to 24% for KrF and for 24 to 26% for XeCl lights. Samples were irradiated by a single shot of KrF excimer-laser light pulse after dehydrogenation. Details of the ELA apparatus were reported elsewhere [8]. The micro-structural analyses of the crystallized Si films were performed by means of a SEM after Secco-etching.

The lengths were the same for both samples as shown in Fig.3. since the total heat energy stored was the same for both samples. But the irradiated light intensity reduced from 660 mJ/cm<sup>2</sup> to 480 mJ/cm<sup>2</sup>.

In conclusion, we have changed the value of the absorption coefficient  $\alpha$  and have obtained a long lateral growth of more than 5μm with reduced light intensity by introducing a SiO<sub>x</sub> capping layer. The capping layer, consisting of SiO<sub>x</sub>, is a promising candidate not only for KrF excimer-laser but also for XeCl excimer-laser.

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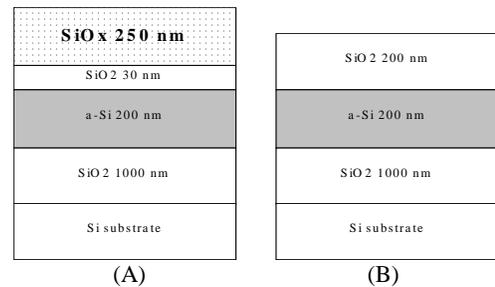


Fig. 1 Schematics of the sample structures  
(A) SiO<sub>x</sub>/SiO<sub>2</sub> double capping layers  
(B) SiO<sub>2</sub> capping layer (reference)

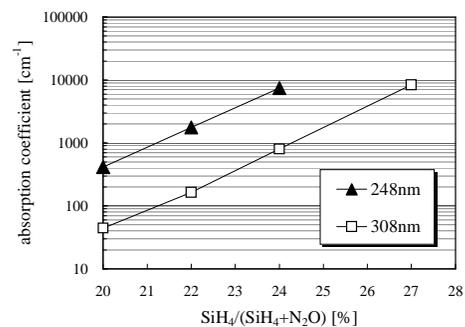


Fig.2 Absorption coefficients of SiO<sub>x</sub> film versus the flow rate ratio of SiH<sub>4</sub> and N<sub>2</sub>O.

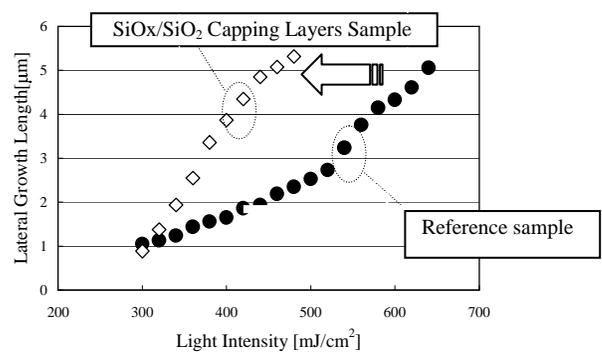


Fig.3 Lateral growth length as a function of light intensity.